

OSMM&N File No. 245724US2X

Serial No. 10/717,718

In the matter of the Application of: Yasutaka NISHIOKA, et al.

For: ELECTRONIC DEVICE MANUFACTURING METHOD

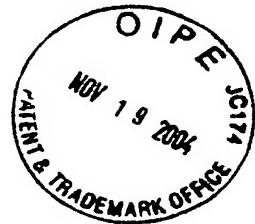
Dept.: E/M

By: EHK/PAS/jyh

Due Date: N/A

The following has been received in the U.S. Patent Office on the date stamped hereon:

- Dep. Acct. Order Form
- Cover Letter
- Petition For Consideration Under 37 CFR 1.181(a)(3)
- Date-Stamped Filing Receipt dated November 21, 2003 (Copy)
- Information Disclosure Statement filed on November 21, 2003 (Copy)
- Form PTO-1449 filed on November 21, 2003 (Copy)



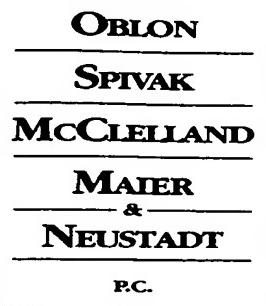
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DATE ALLOWED: October 20, 2004

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313



ATTORNEYS AT LAW

Docket No.: 245724US2X

RE: Application Serial No.: 10/717,718

Inventor: Yasutaka NISHIOKA, et al.

Filing Date: November 21, 2003

For: ELECTRONIC DEVICE MANUFACTURING METHOD

Group: 3729

Examiner: Carl J. ARBES

SIR:

Attached hereto for filing are the following papers:

**PETITION FOR CONSIDERATION UNDER 37 CFR §1.181(a)(3)
DATE-STAMPED FILING RECEIPT DATED NOVEMBER 21, 2003 (COPY)
INFORMATION DISCLOSURE STATEMENT FILED ON NOVEMBER 21, 2003 (COPY)
FORM PTO 1449 FILED ON NOVEMBER 21, 2003 (COPY)**

Our credit card form in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 CFR 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 CFR 1.136 for the necessary extension of time.

Respectfully Submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Eckhard H. Kuesters
Registration No. 28,870

Customer Number

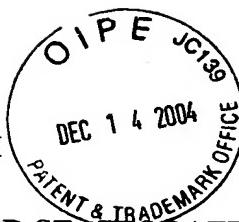
22850

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(OSMMN 05/04)

Paul A. Sacher
Registration No. 43,418

CCPY

DOCKET NO: 245724US2X



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

YASUTAKA NISHIOKA, ET AL. : EXAMINER: CARL J. ARBES

SERIAL NO: 10/717,718 :

FILED: NOVEMBER 21, 2003 : GROUP ART UNIT: 3729

FOR: ELECTRONIC DEVICE
MANUFACTURING METHOD :

PETITION FOR CONSIDERATION UNDER 37 CFR §1.181(a)(3) RE:

INFORMATION DISCLOSURE STATEMENT FILING(S)

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

This is a Petition pursuant to 37 CFR §1.181(a)(3) requesting that the Examiner be instructed by the Commissioner or his representative to notify Applicants of proper consideration of the information disclosure statement (IDS) that was filed on November 21, 2003.

STATEMENT OF FACTS

On November 21, 2003, Applicants filed the above-noted IDS under 37 CFR §§1.97 and 1.98, which filing is clearly documented by the attached copy of the associated date-stamped Mail Room receipt and copies of the IDS papers including the Form PTO 1449 and cited references (4). The PTO has not responded to this IDS filing by supplying Applicants with a copy of the Form PTO 1449 filed on November 21, 2003, that has been properly initialed by the Examiner.

COPY

POINT FOR REVIEW

The point for review is why Applicants have not been provided a copy of the above-noted Form PTO 1449 filed on November 21, 2003, properly initialed by the Examiner in compliance with the rules.

ACTION REQUESTED

In light of the above, it is respectfully requested that the Examiner be directed to provide Applicants a copy of the above-noted Form PTO 1449 filed on November 21, 2003, properly initialed by the Examiner in compliance with the rules.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND
MAIER & NEUSTADT, P.C.

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(OSMMN 06/04)

GJM/PAS/jyh

Eckhard H. Kuesters
Registration No. 28,870
Attorney of Record

Paul A. Sacher
Registration No. 43,418

COPY



fm.

OSMM&N File No. 245724US2X

Dept.: PP/JF

By: MJS/als

Serial No. New Application

In the matter of the Application of: Yasutaka NISHIOKA, et al.

For: ELECTRONIC DEVICE MANUFACTURING METHOD

Due Date: 1/21/04

The following has been received in the U.S. Patent Office on the date stamped hereon:

- 35 pp. Specification 20 Claims/Drawings 16 Sheets and
3 Pages Application Data Sheet
- Combined Declaration, Petition & Power of Attorney 4 Pages
- Utility Patent Application Transmittal
- Request for Priority ■ Priority Doc 1
- Credit Card Form for \$810.00 ■ Dep. Acct. Order Form
- Fee Transmittal Form
- Assignment/PTO 1595 Pages: 3
- Information Disclosure Statement ■ PTO-1449
- Cited References 4
- White Advance Serial Number Card



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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Yasutaka NISHIOKA, et al.

SERIAL NO: New Application

GAU:

FILED: Herewith

EXAMINER:

FOR: ELECTRONIC DEVICE MANUFACTURING METHOD

DEC 14 2004

PATENT & TRADEMARK
OFFICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

- Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.

Marvin J. Spivak
Registration No. 24,913

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(OSMMN 05/03)

COPY

Form PTO 1449 (Modified)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY DOCKET NO. 245724US2X		SERIAL NO. New Application	
LIST OF REFERENCES CITED BY APPLICANT DEC 14 2004		O P T E P A T E N T & T R A D E M A R K O F F I C E S		APPLICANT Yasutaka NISHIOKA, et al.			
				FILING DATE Herewith		GROUP	
U.S. PATENT DOCUMENTS							
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						
	AL						
	AM						
	AN						
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	TRANSLATION		
	AO	2000-269326	9/29/00	Japan (with English Extract)	YES	NO	X
	AP						
	AQ						
	AR						
	AS						
	AT						
	AU						
	AV						
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AW	S. M. JANG, et al., "INTEGRATION OF CU AND LOW-K MATERIAL FOR DUAL-DAMASCENE PROCESS", Semiconductor Technology, (ISTC 2001), Vol. I, Pages 485-493					
	AX	K. HIGASHI, et al., "A MANUFACTURABLE COPPER/LOW-K SiOC/SiCN PROCESS TECHNOLOGY FOR 90NM-NODE HIGH PERFORMANCE eDRAM", Proceedings of the 2002 International Interconnect Technology Conference, Pages 15-17					
	AY	M. FAYOLLE, et al., "INTEGRATION OF Cu/SiOC IN DUAL DAMASCENE INTERCONNECT FOR 0.1µm TECHNOLOGY USING A NEW SiC MATERIAL AS DIELECTRIC BARRIER", Proceedings of the 2002 International Interconnect Technology Conference, Pages 39-41					
	AZ					<input type="checkbox"/> Additional References sheet(s) attached	
Examiner						Date Considered	
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							

COPY